DATASHEET

Technical Data Sheet
Top Infrared LED
IR67-21C/L261/S58/8T8

Features

- Compatible with infrared and vapor phase reflow solder process.
- Low forward voltage.
- View angle 120°
- Pb free
- The product itself will remain within RoHS compliant version.
- Compliance with EU REACH.
- Compliance Halogen Free .(Br <900 ppm ,Cl <900 ppm , Br+Cl < 1500 ppm)

Description

IR67-21C/L261/S58/8T8 is an infrared emitting diode in miniature SMD package which is molded in a water clear plastic with flat top view lens.
The device is spectrally matched with silicon photodiode and phototransistor.

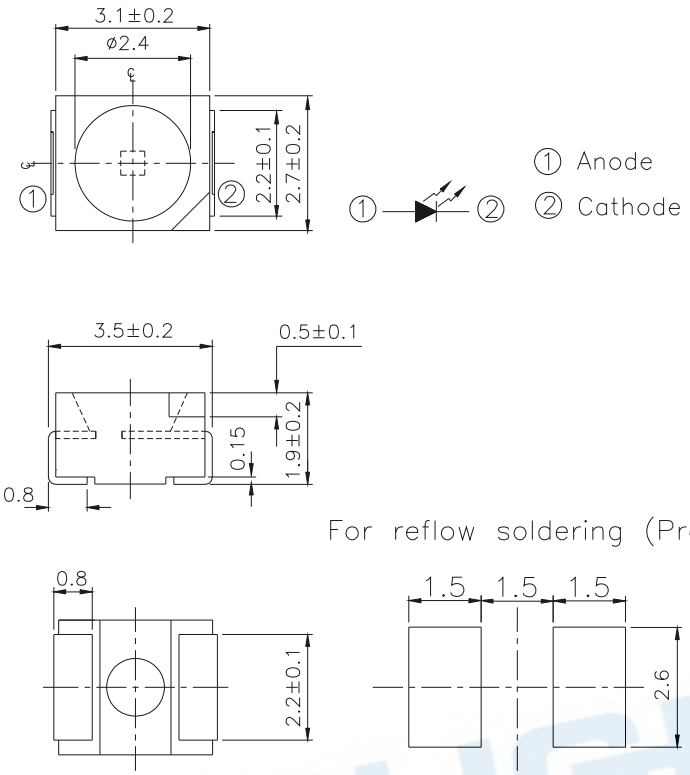
Applications

- Sensor
- Optoelectronic switch
- Camera
- VCR
- Video
- Smoke detector

Device Selection Guide

Device No.	Chip Material	Lens Color
IR67-21C/L261/S58/8T8	GaAlAs	Water clear

Package Dimensions



Notes: 1.All dimensions are in millimeters
2.Tolerances unless dimensions ±0.1mm

Absolute Maximum Ratings (Ta=25℃)

Parameter	Symbol	Rating	Unit
Continuous Forward Current	I_F	65	mA
Peak Forward Current *1	I_{FP}	1	A
Surge Forward Current *2	I_{FS}	2	A
Reverse Voltage	V_R	5	V
Operating Temperature	T_{opr}	-40~ +85	℃
Storage Temperature	T_{stg}	-40 ~ +100	℃
Soldering Temperature *3	T_{sol}	260	℃
Power Dissipation at(or below)	P_d	130	mW
25℃ Free Air Temperature	Rthj-a	400	℃/W

Notes: *1:I_{FP} Conditions--Pulse Width≦100 μs and Duty≦1%.
*2:I_{FS} Conditions--Pulse Width≦100 μs
*3:Soldering time≦5 seconds.

Electro-Optical Characteristics (Ta=25℃ unless specified otherwise)

Parameter	Symbol	Min.	Typ.*	Max.	Unit	Condition
Radiant Intensity	I_E	1.0	2.0	3.5	mW/sr	I_F=20mA
		4	8	--		I_F=100mA Pulse Width≦100μs ,Duty ≦1%
Total Radiated Power	Po	--	20	--	mW	I_F=100mA
Peak Wavelength	λp	--	940	--	nm	I_F=20mA
Spectral Bandwidth	Δλ	--	50	--	nm	I_F=20mA
Forward Voltage	V_F	--	1.20	1.60	V	I_F=20mA
		--	1.45	1.80		I_F=100mA Pulse Width≦100μs ,Duty ≦1%
Reverse Current	I_R	--	--	10	μA	V_R=5V
View Angle	2θ1/2	--	120	--	deg	I_F=20mA
Active chip area	A		0.122		mm^2	----
Dimensions of the active chip area	L×W		0.350*0.350		mm×mm	----

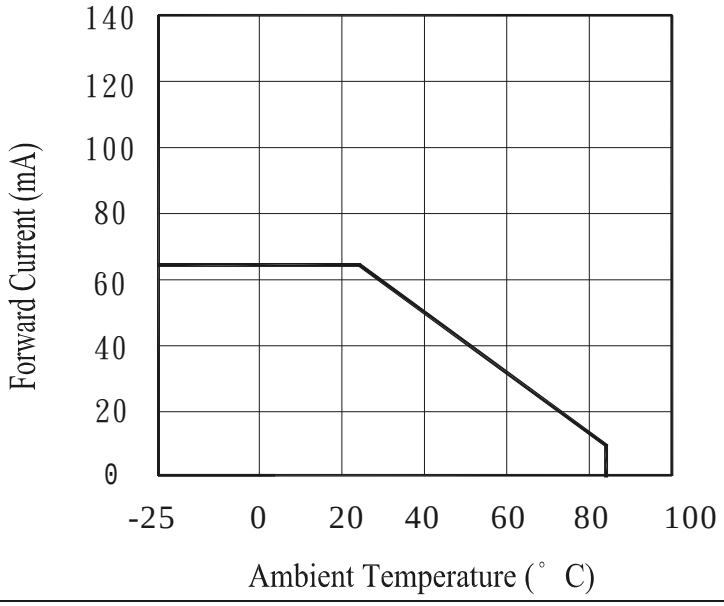
Rank

Condition：I_F=20mA
Unit：mW/sr

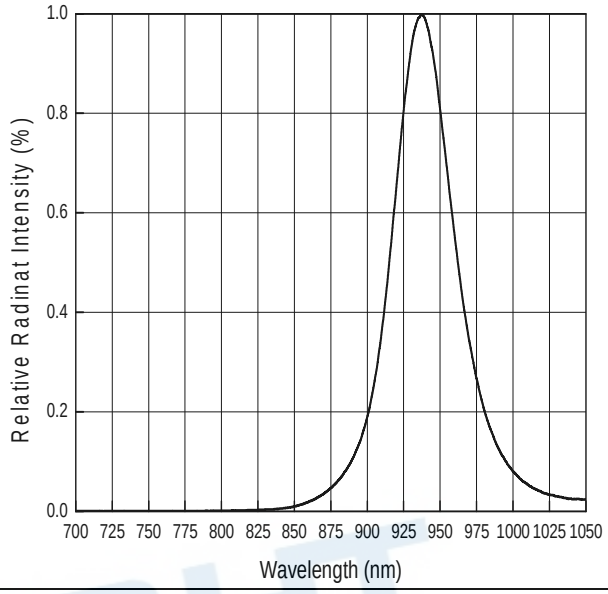
Bin Number	G	H.
Min	1.0	2.0
Max	2.5	3.5

Typical Electrical/Optical/Characteristics Curves

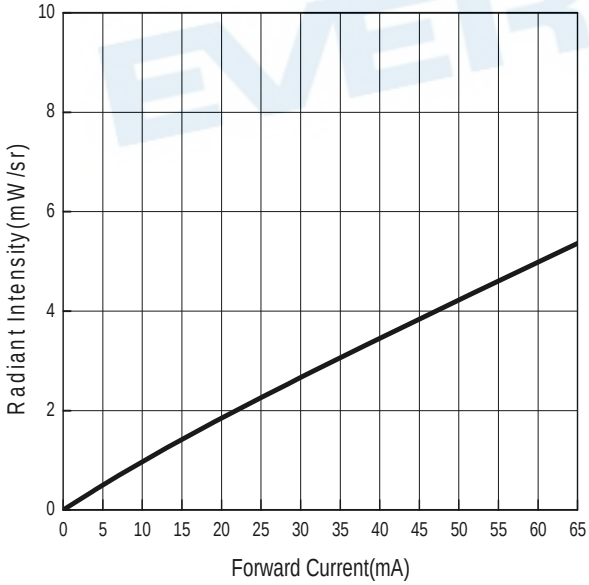
Forward Current vs. Ambient Temperature



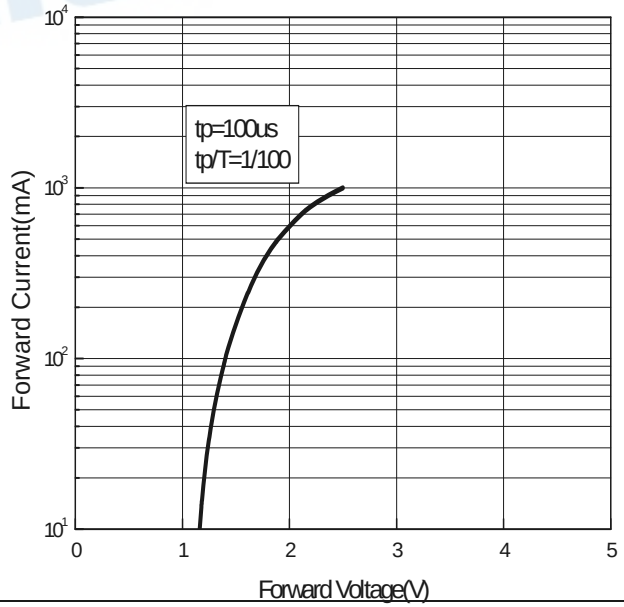
Spectral Distribution



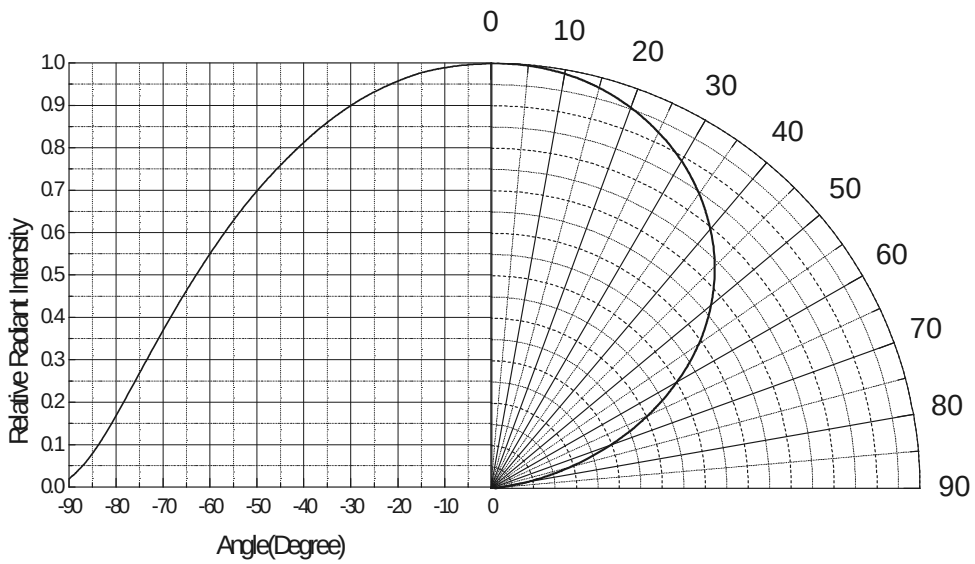
Radiant Intensity vs Forward Current



Forward Current vs. Forward Voltage



Relative Radiant Intensity vs. Angular Displacement



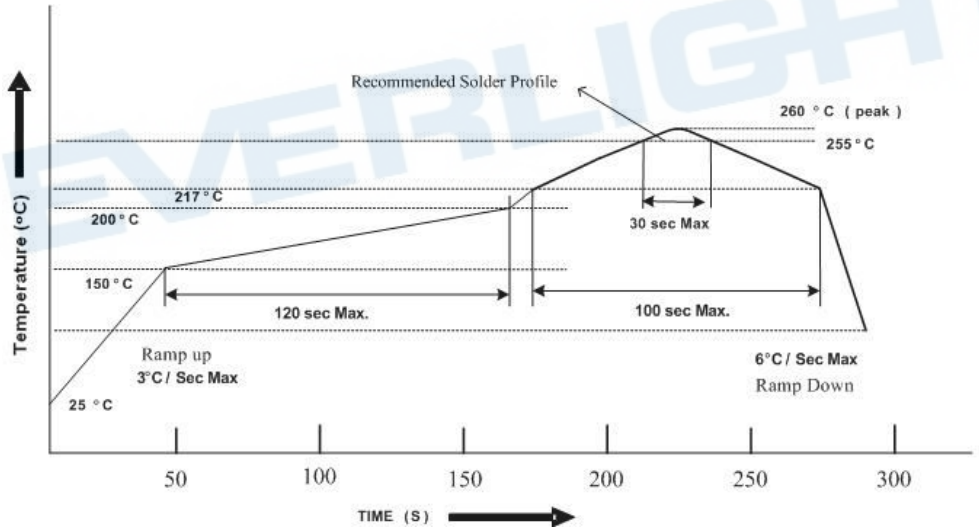
Precautions For Use

1. Over-current-proof

   Customer must apply resistors for protection , otherwise slight voltage shift will cause big current change (Burn out will happen).

2. Storage
   2.1 Do not open moisture proof bag before the products are ready to use.
   2.2 Before opening the package, the LEDs should be kept at 30℃ or less and 90%RH or less.
   2.3 The LEDs should be used within a year.
   2.4 After opening the package, the LEDs should be kept at 30℃ or less and 60%RH or less.
   2.5 The LEDs should be used within 168 hours (7 days) after opening the package
   2.6 If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.
   Baking treatment : 60±5℃ for Min. 24 hours.

3. Soldering Condition
   3.1 Pb-free solder temperature profile



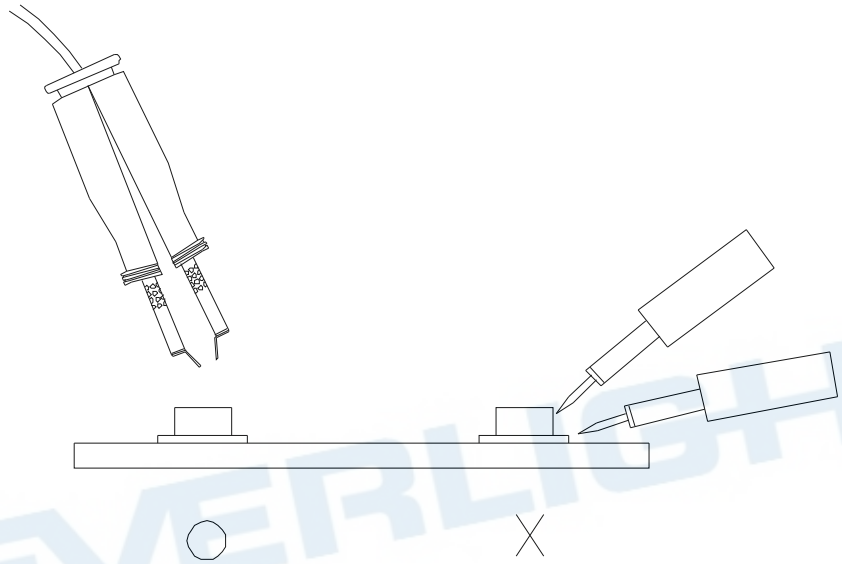
   3.2 Reflow soldering should not be done more than two times.
   3.3 When soldering, do not put stress on the LEDs during heating.
   3.4 After soldering, do not warp the circuit board.

4. Soldering Iron

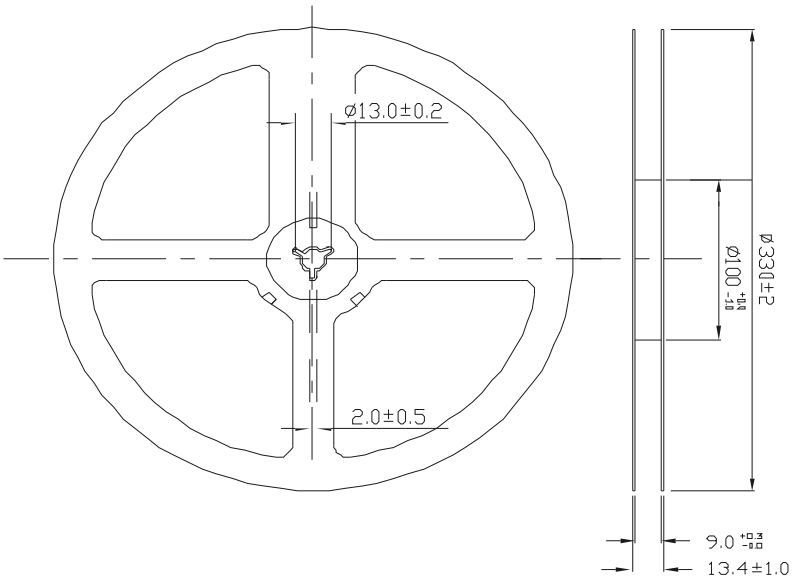
Each terminal is to go to the tip of soldering iron temperature less than 350℃ for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

5. Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.

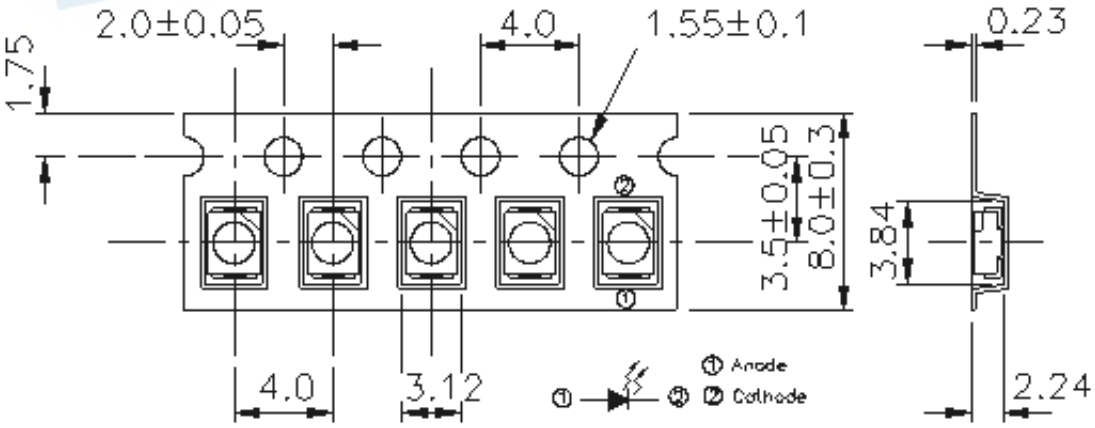


Package Dimensions



Note: The tolerances unless mentioned is ±0.1mm ,Unit = mm

Carrier Tape Dimensions:(Quantity: 8000pcs/reel)



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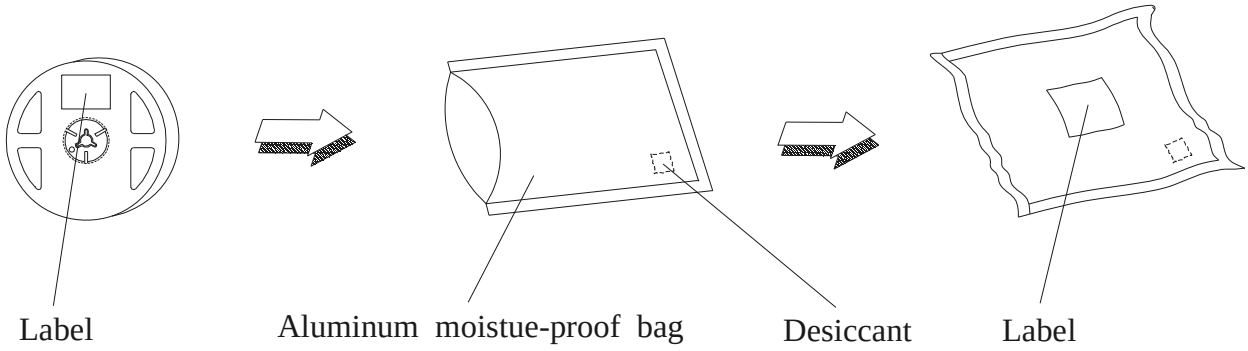
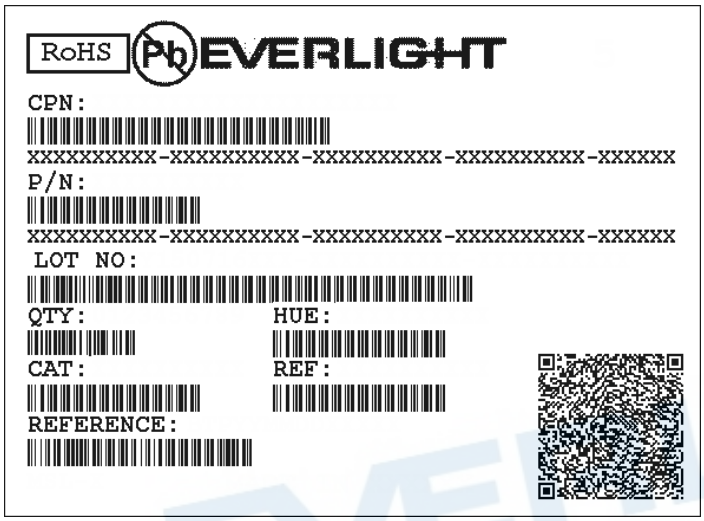
Packing Procedure



Label Form Specification



CPN: Customer's Production Number
P/N : Production Number
QTY: Packing Quantity
CAT: Ranks
HUE: Peak Wavelength
REF: Reference
LOT No: Lot Number
MADE IN TAIWAN: Production Place

DISCLAIMER

1. EVERLIGHT reserves the right(s) on the adjustment of product material mix for the specification.
2. The product meets EVERLIGHT published specification for a period of twelve (12) months from date of shipment.
3. The graphs shown in this datasheet are representing typical data only and do not show guaranteed values.
4. When using this product, please observe the absolute maximum ratings and the instructions for using outlined in these specification sheets. EVERLIGHT assumes no responsibility for any damage resulting from the use of the product which does not comply with the absolute maximum ratings and the instructions included in these specification sheets.
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